

N-channel 800 V, 0.19  $\Omega$  typ., 19.5 A MDmesh™ K5 Power MOSFETs  
in D<sup>2</sup>PAK, TO-220FP, TO-220 and TO-247 packages

Datasheet – production data

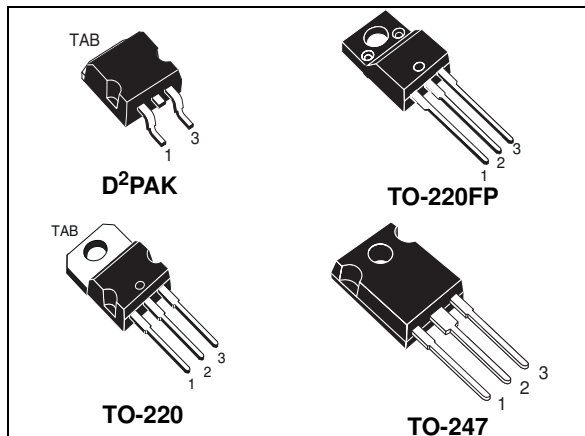
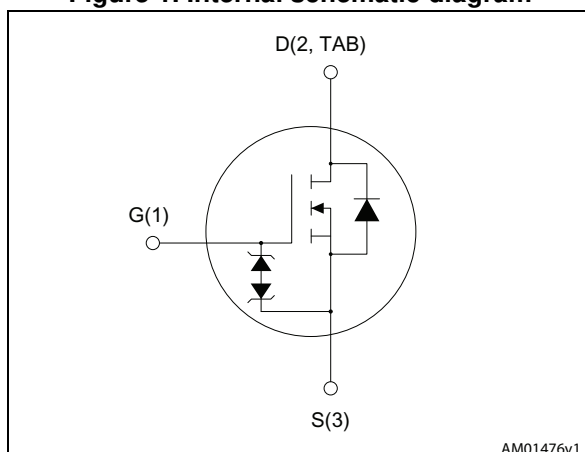


Figure 1. Internal schematic diagram



## Features

Order code	$V_{DS}$ @ $T_{Jmax}$	$R_{DS(on)}$ max	$I_D$	$P_{TOT}$
STB25N80K5	800 V	< 0.260 $\Omega$	19.5 A	250 W
STF25N80K5				40 W
STP25N80K5				250 W
STW25N80K5				

- Industry's lowest  $R_{DS(on)}$  x area
- Industry's best figure of merit (FoM)
- Ultra low gate charge
- 100% avalanche tested
- Zener-protected

## Applications

- Switching applications

## Description

These very high voltage N-channel Power MOSFETs are designed using MDmesh™ K5 technology based on an innovative proprietary vertical structure. The result is a dramatic reduction in on-resistance and ultra-low gate charge for applications requiring superior power density and high efficiency.

Table 1. Device summary

Order code	Marking	Package	Packaging
STB25N80K5	25N80K5	D <sup>2</sup> PAK	Tape and reel
STF25N80K5		TO-220FP	Tube
STP25N80K5		TO-220	
STW25N80K5		TO-247	

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# 1 Electrical ratings

**Table 2. Absolute maximum ratings**

Symbol	Parameter	Value		Unit
		D <sup>2</sup> PAK, TO-220, TO-247	TO-220FP	
V <sub>GS</sub>	Gate- source voltage	± 30		V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	19.5	19.5 <sup>(1)</sup>	A
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 100 °C	12.3	12.3 <sup>(1)</sup>	A
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	78	78 <sup>(1)</sup>	A
P <sub>TOT</sub>	Total dissipation at T <sub>C</sub> = 25 °C	250	40	W
I <sub>AR</sub>	Max current during repetitive or single pulse avalanche (pulse width limited by T <sub>jmax</sub> )	6.5		A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>J</sub> = 25 °C, I <sub>D</sub> =I <sub>AS</sub> , V <sub>DD</sub> = 50 V)	200		mJ
V <sub>iso</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t=1 s; T <sub>C</sub> =25 °C)		2500	V
dv/dt <sup>(3)</sup>	Peak diode recovery voltage slope	6		V/ns
T <sub>j</sub> T <sub>stg</sub>	Operating junction temperature Storage temperature	-55 to 150		°C

- Limited by package.
- Pulse width limited by safe operating area.
- I<sub>SD</sub> ≤ 19.5 A, di/dt ≤ 100 A/μs, V<sub>Peak</sub> ≤ V<sub>(BR)DSS</sub>

**Table 3. Thermal data**

Symbol	Parameter	Value				Unit
		TO-220	TO-247	D <sup>2</sup> PAK	TO-220FP	
R <sub>thj-case</sub>	Thermal resistance junction-case max	0.5			3.1	°C/W
R <sub>thj-amb</sub>	Thermal resistance junction-amb max	62.5	50		62.5	
R <sub>thj-pcb</sub> <sup>(1)</sup>	Thermal resistance junction-pcb max			30		

- When mounted on 1inch<sup>2</sup> FR-4 board, 2 oz Cu.

## 2 Electrical characteristics

( $T_{CASE} = 25\text{ °C}$  unless otherwise specified).

**Table 4. On/off states**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage ( $V_{GS} = 0$ )	$I_D = 1\text{ mA}$	800			V
$I_{DSS}$	Zero gate voltage drain current ( $V_{GS} = 0$ )	$V_{DS} = 800\text{ V}$			1	$\mu\text{A}$
		$V_{DS} = 800\text{ V}, T_C = 125\text{ °C}$			50	$\mu\text{A}$
$I_{GSS}$	Gate body leakage current ( $V_{DS} = 0$ )	$V_{GS} = \pm 20\text{ V}$			$\pm 10$	$\mu\text{A}$
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}, I_D = 100\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}, I_D = 10\text{ A}$		0.19	0.260	$\Omega$

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 100\text{ V}, f = 1\text{ MHz}, V_{GS} = 0$	-	1600	-	pF
$C_{oss}$	Output capacitance		-	130	-	pF
$C_{rss}$	Reverse transfer capacitance		-	2	-	pF
$C_{o(tr)}^{(1)}$	Equivalent capacitance time related	$V_{GS} = 0, V_{DS} = 0\text{ to }640\text{ V}$	-	185	-	pF
$C_{o(er)}^{(2)}$	Equivalent capacitance energy related		-	300	-	pF
$R_G$	Intrinsic gate resistance	$f = 1\text{ MHz open drain}$	-	4	-	$\Omega$
$Q_g$	Total gate charge	$V_{DD} = 640\text{ V}, I_D = 19.5\text{ A}$ $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 19</a> )	-	40	-	nC
$Q_{gs}$	Gate-source charge		-	10		nC
$Q_{gd}$	Gate-drain charge		-	25		nC

1. Time related is defined as a constant equivalent capacitance giving the same charging time as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$
2. Energy related is defined as a constant equivalent capacitance giving the same stored energy as  $C_{oss}$  when  $V_{DS}$  increases from 0 to 80%  $V_{DSS}$

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 400\text{ V}$ , $I_D = 10\text{ A}$ , $R_G = 4.7\ \Omega$ , $V_{GS} = 10\text{ V}$ (see <a href="#">Figure 21</a> )	-	25	-	ns
$t_r$	Rise time		-	13	-	ns
$t_{d(off)}$	Turn-off delay time		-	60	-	ns
$t_f$	Fall time		-	15	-	ns

Table 7. Source drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		19.5	A
$I_{SDM}$	Source-drain current (pulsed)		-		78	A
$V_{SD}^{(1)}$	Forward on voltage	$I_{SD} = 19.5\text{ A}$ , $V_{GS} = 0$	-		1.5	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 19.5\text{ A}$ , $V_{DD} = 60\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s}$ , (see <a href="#">Figure 20</a> )	-	515		ns
$Q_{rr}$	Reverse recovery charge		-	11		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	43.2		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 19.5\text{ A}$ , $V_{DD} = 60\text{ V}$ $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 150\text{ }^\circ\text{C}$ (see <a href="#">Figure 20</a> )	-	615		ns
$Q_{rr}$	Reverse recovery charge		-	13		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current		-	43		A

1. Pulsed: pulse duration = 300 $\mu\text{s}$ , duty cycle 1.5%

Table 8. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1\text{ mA}$ , $I_D = 0$	30	-	-	V

The built-in back-to-back Zener diodes have been specifically designed to enhance the ESD capability of the device. The Zener voltage is appropriate for efficient and cost-effective intervention to protect the device integrity. These integrated Zener diodes thus eliminate the need for external components.

## 2.1 Electrical characteristics (curves)

Figure 2. Safe operating area for D<sup>2</sup>PAK

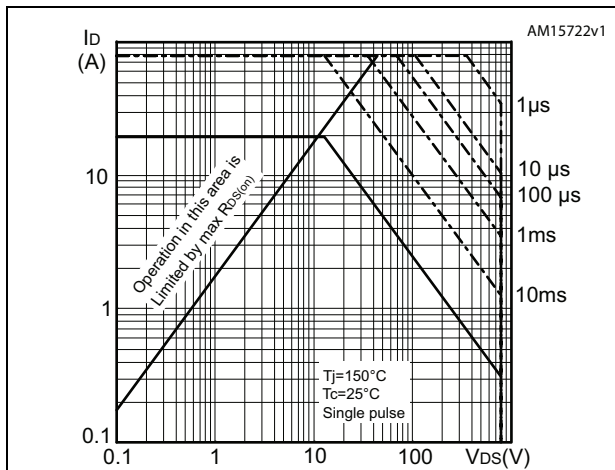


Figure 3. Thermal impedance for D<sup>2</sup>PAK and TO-220

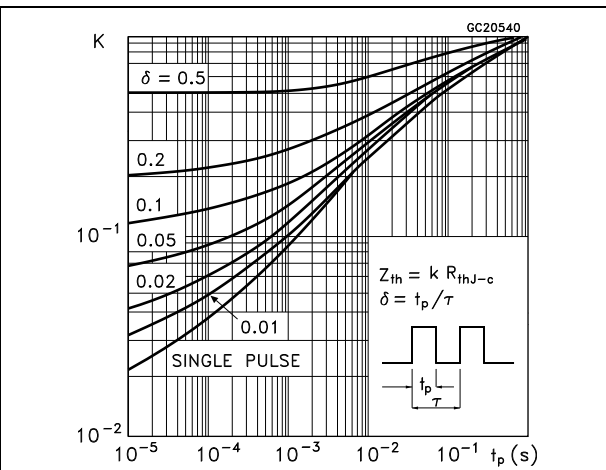


Figure 4. Safe operating area for TO-220FP

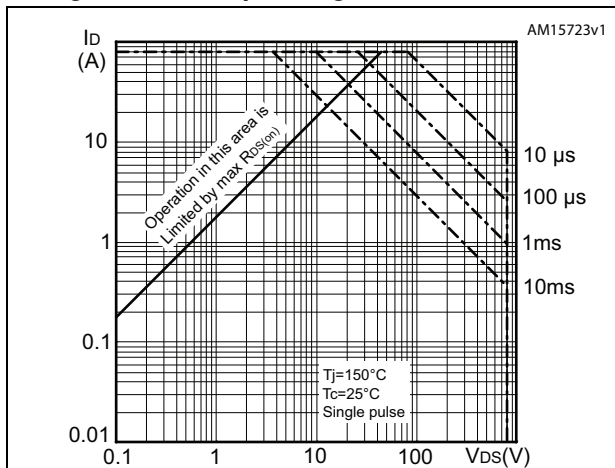


Figure 5. Thermal impedance for TO-220FP

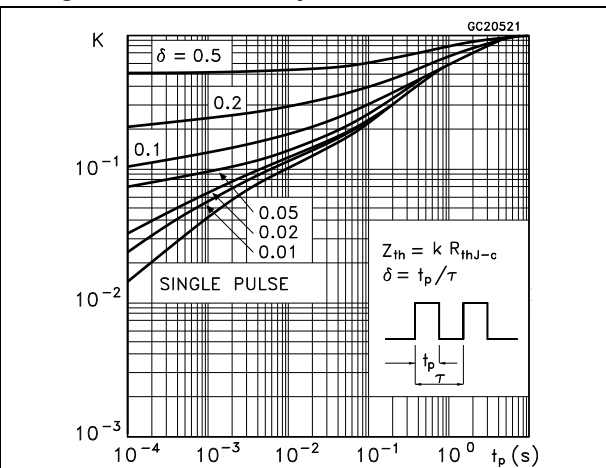


Figure 6. Safe operating area for TO-220

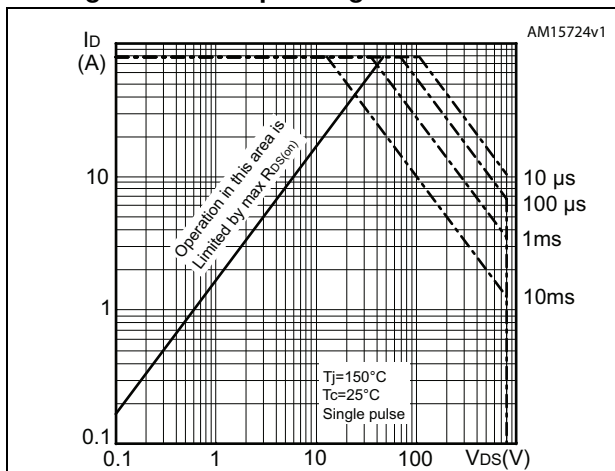


Figure 7. Normalized  $B_{VDSS}$  vs temperature

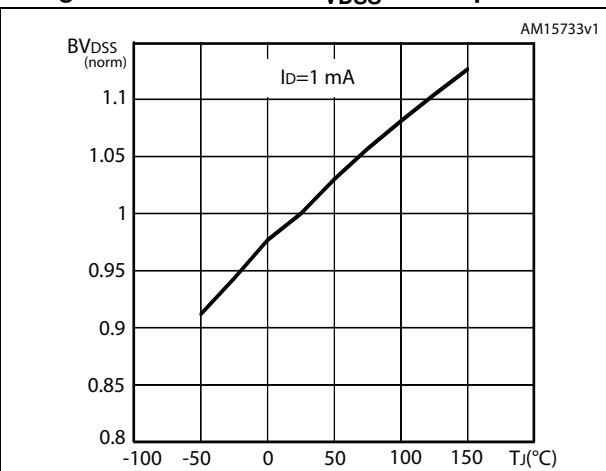


Figure 8. Safe operating area for TO-247

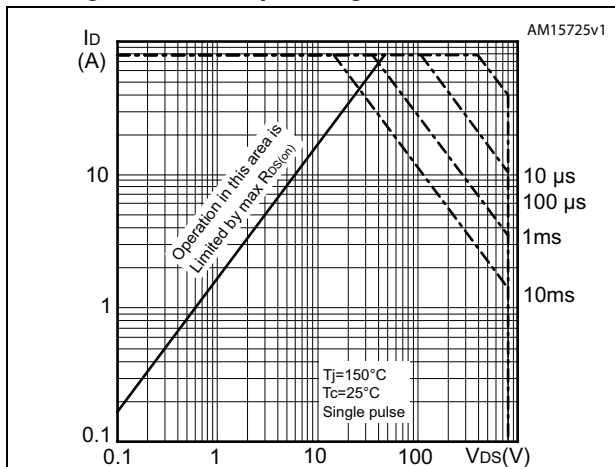


Figure 9. Thermal impedance for TO-247

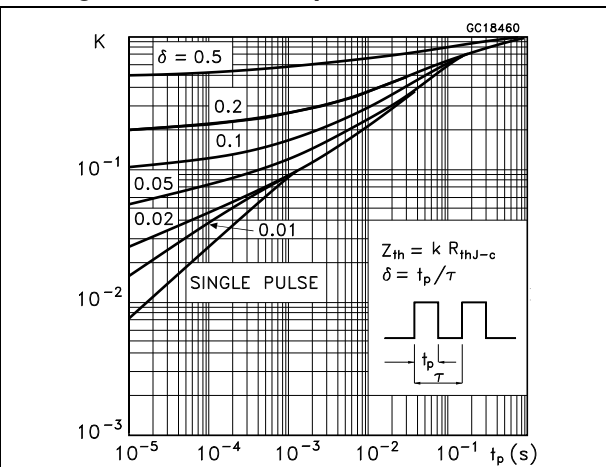


Figure 10. Output characteristics

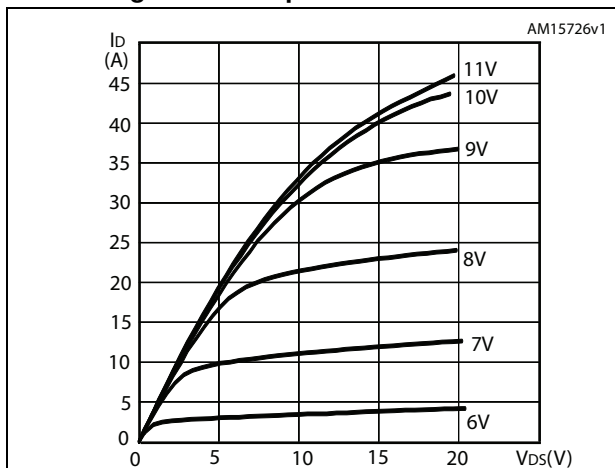


Figure 11. Transfer characteristics

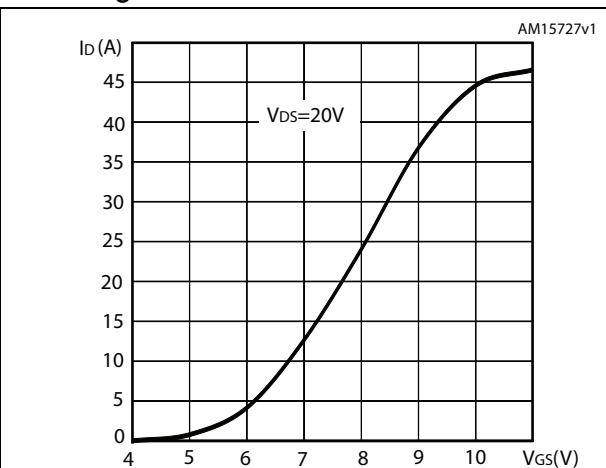


Figure 12. Static drain-source on-resistance

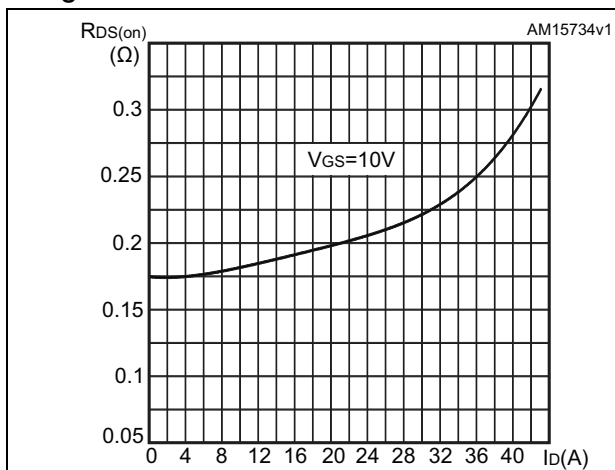


Figure 13. Gate charge vs gate-source voltage

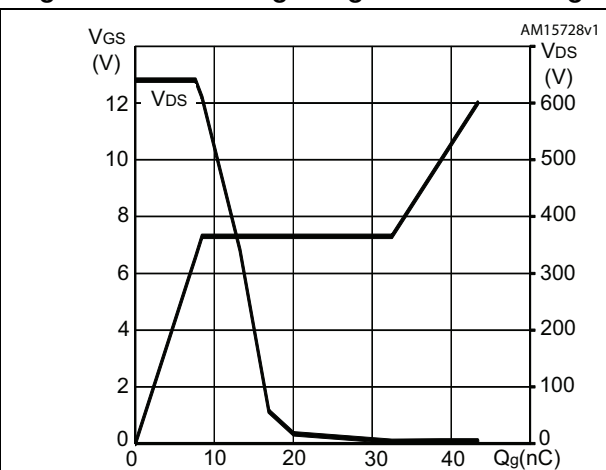


Figure 14. Capacitance variations

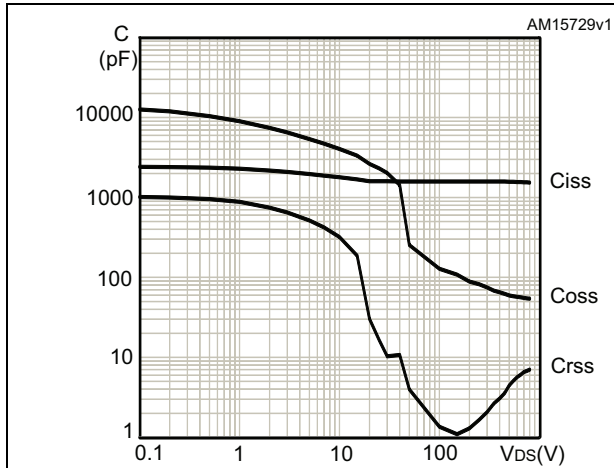


Figure 15. Output capacitance stored energy

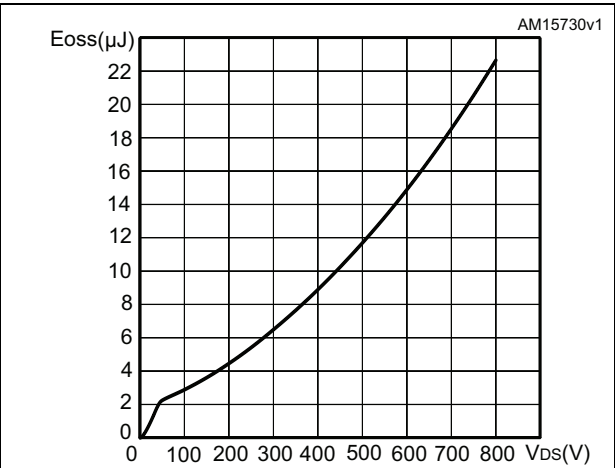


Figure 16. Normalized on-resistance vs temperature

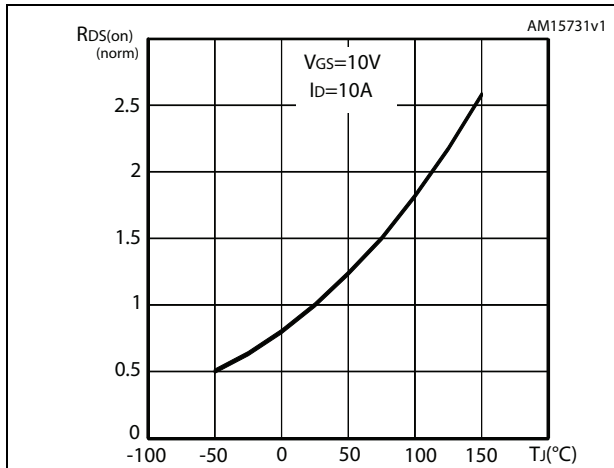
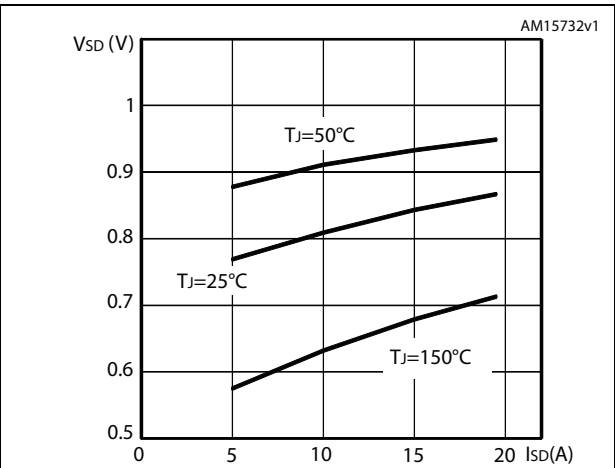


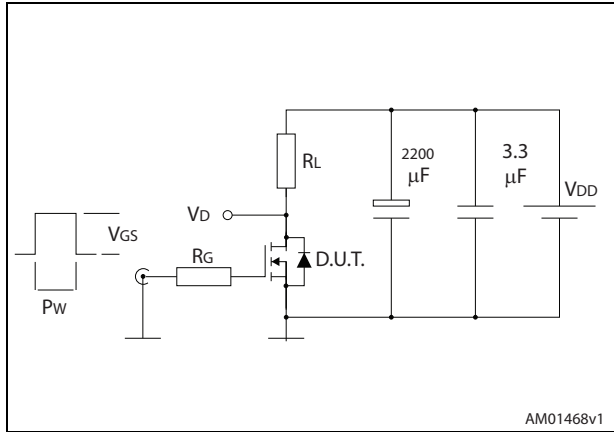
Figure 17. Source-drain diode forward characteristics





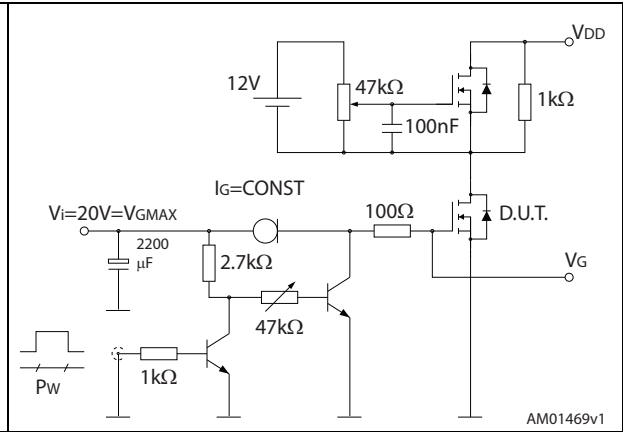
### 3 Test circuits

**Figure 18. Switching times test circuit for resistive load**



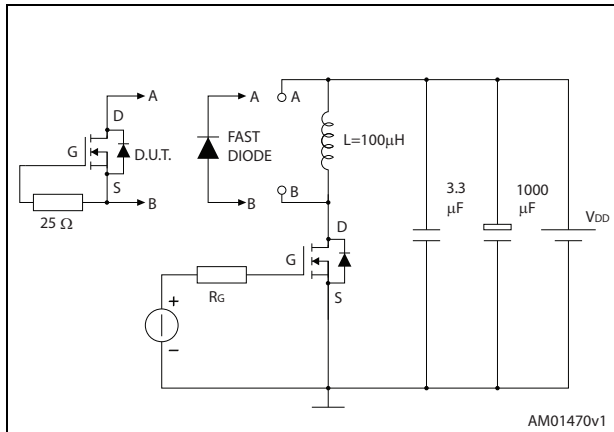
AM01468v1

**Figure 19. Gate charge test circuit**



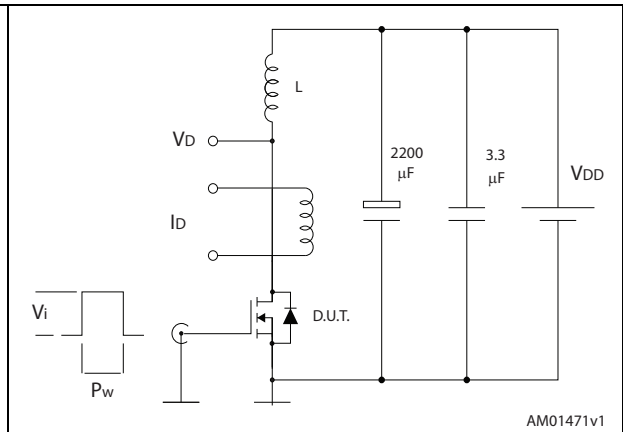
AM01469v1

**Figure 20. Test circuit for inductive load switching and diode recovery times**



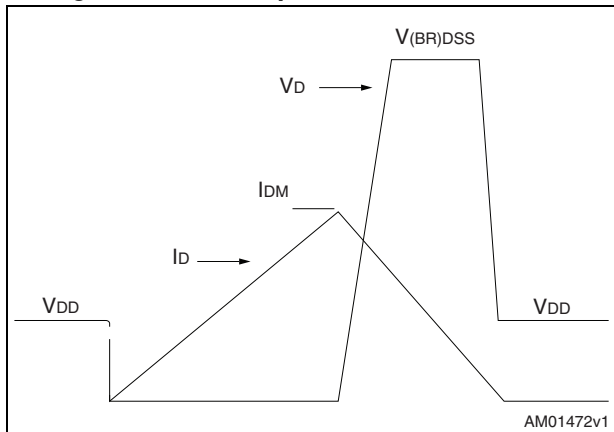
AM01470v1

**Figure 21. Unclamped inductive load test circuit**



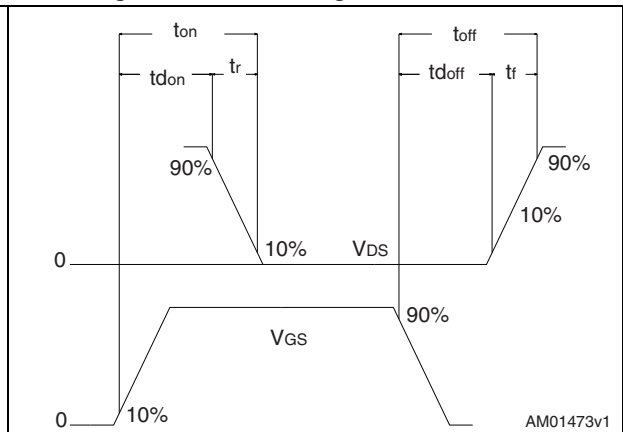
AM01471v1

**Figure 22. Unclamped inductive waveform**



AM01472v1

**Figure 23. Switching time waveform**



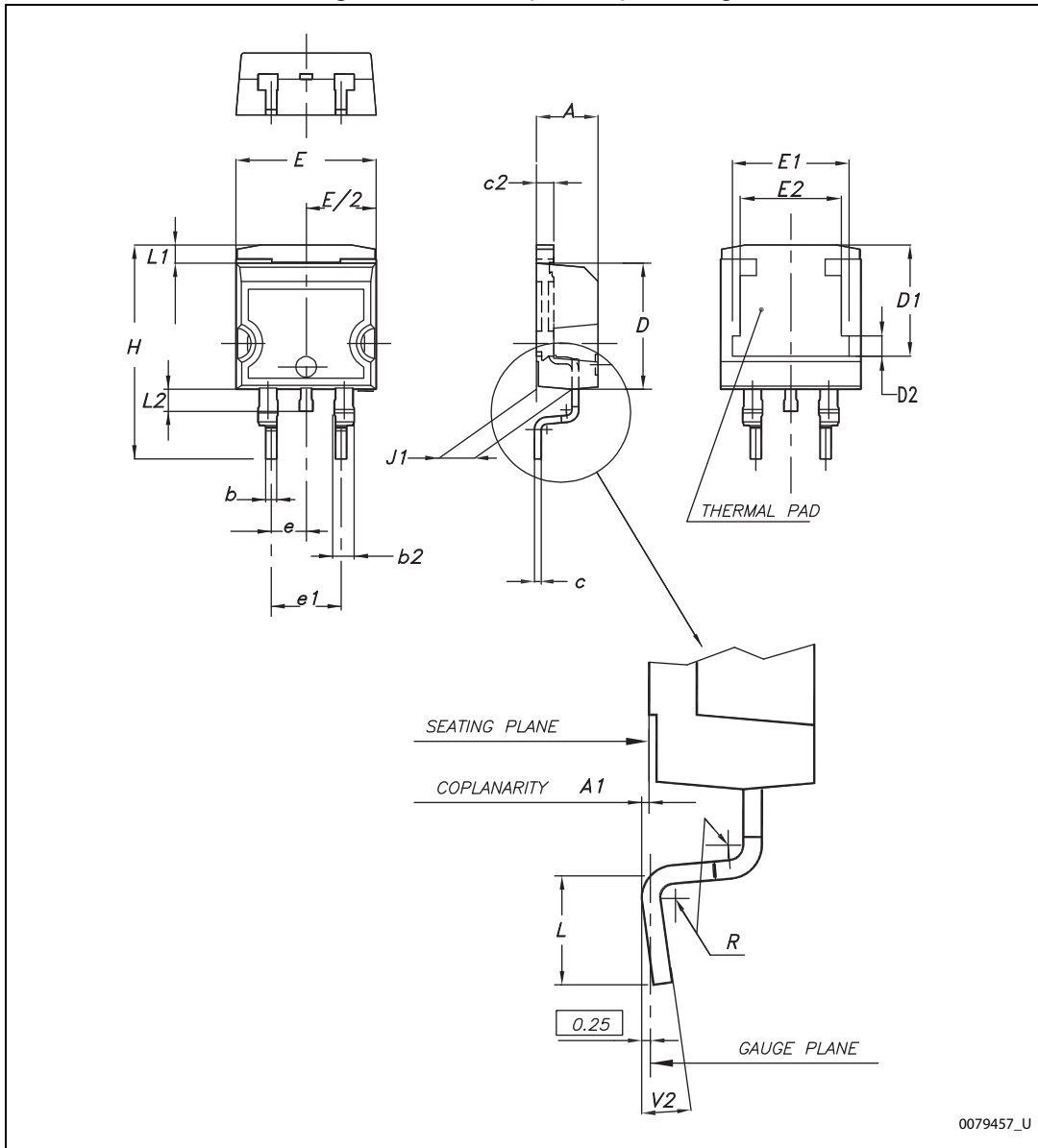
AM01473v1

## 4 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK<sup>®</sup> is an ST trademark.

4.1 STB25N80K5, D<sup>2</sup>PAK

Figure 24. D<sup>2</sup>PAK (TO-263) drawing

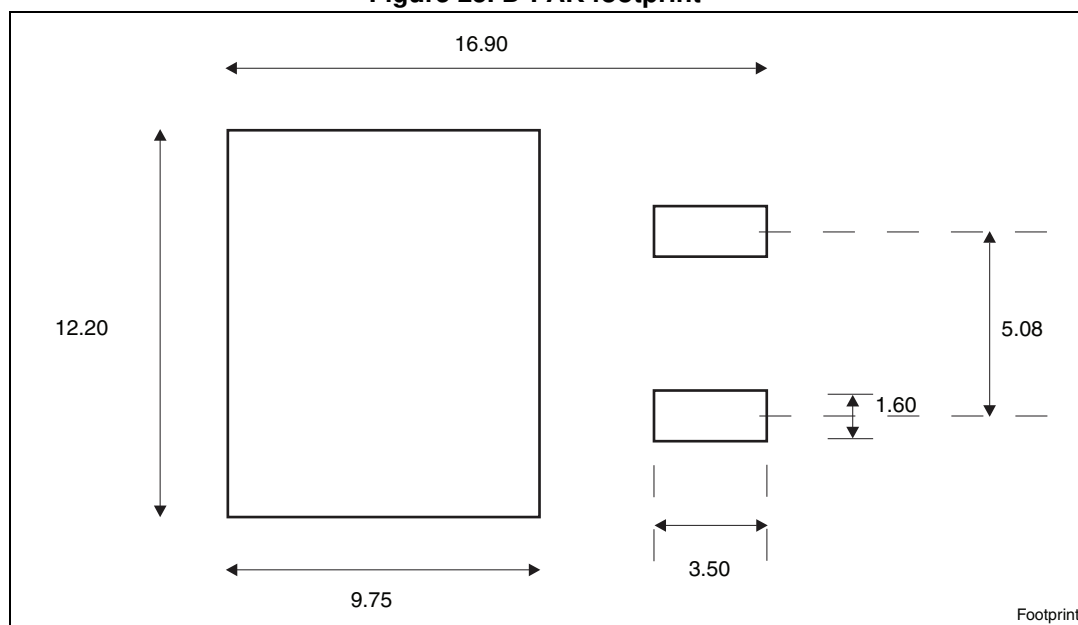


0079457\_U

Table 9. D<sup>2</sup>PAK (TO-263) mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
A1	0.03		0.23
b	0.70		0.93
b2	1.14		1.70
c	0.45		0.60
c2	1.23		1.36
D	8.95		9.35
D1	7.50	7.75	8.00
D2	1.10	1.30	1.50
E	10		10.40
E1	8.50	8.70	8.90
E2	6.85	7.05	7.25
e		2.54	
e1	4.88		5.28
H	15		15.85
J1	2.49		2.69
L	2.29		2.79
L1	1.27		1.40
L2	1.30		1.75
R		0.4	
V2	0°		8°

Figure 25. D<sup>2</sup>PAK footprint<sup>(a)</sup>



a. All dimension are in millimeters

### 4.2 STF25N80K5, TO-220FP

Figure 26. TO-220FP drawing

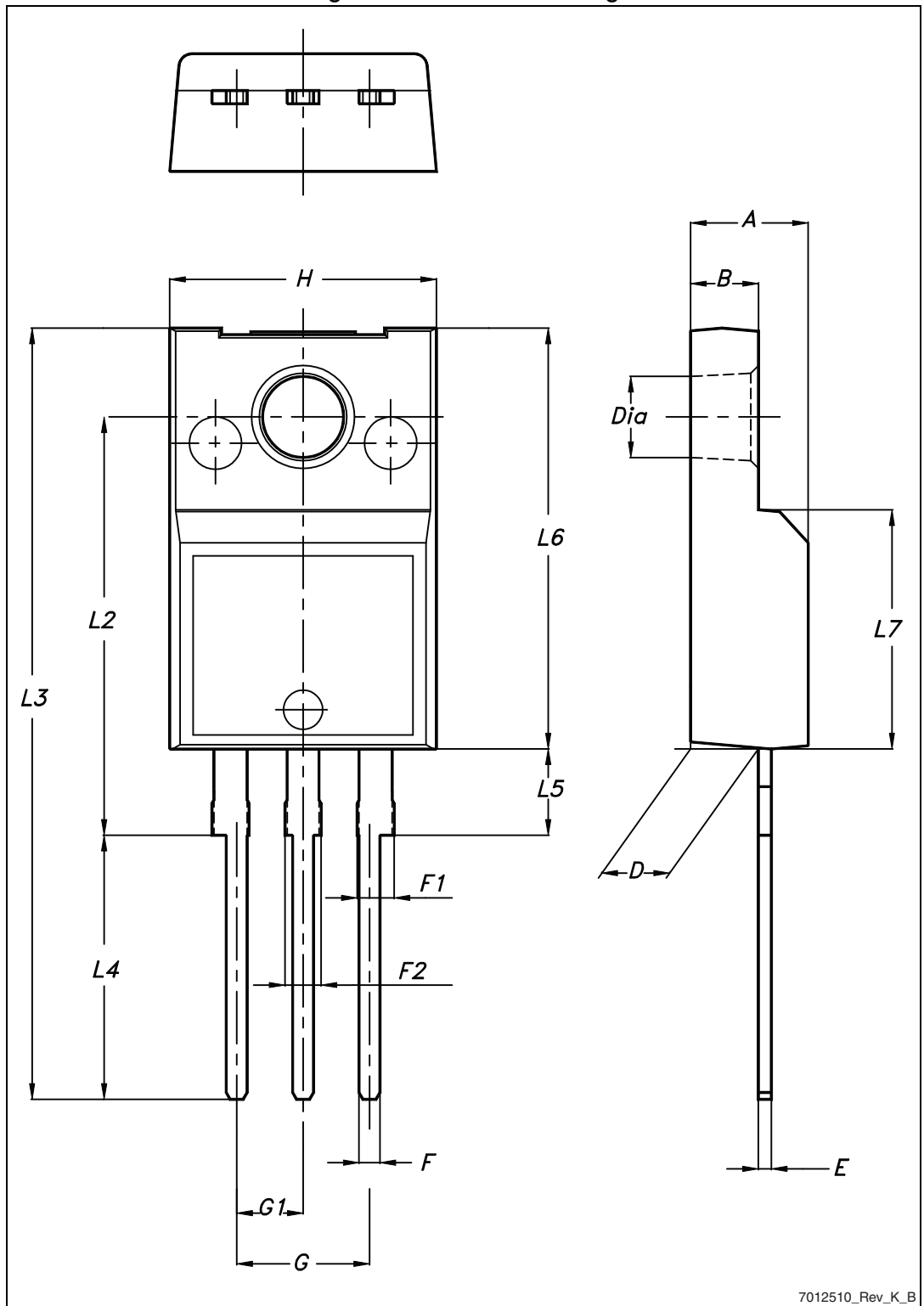
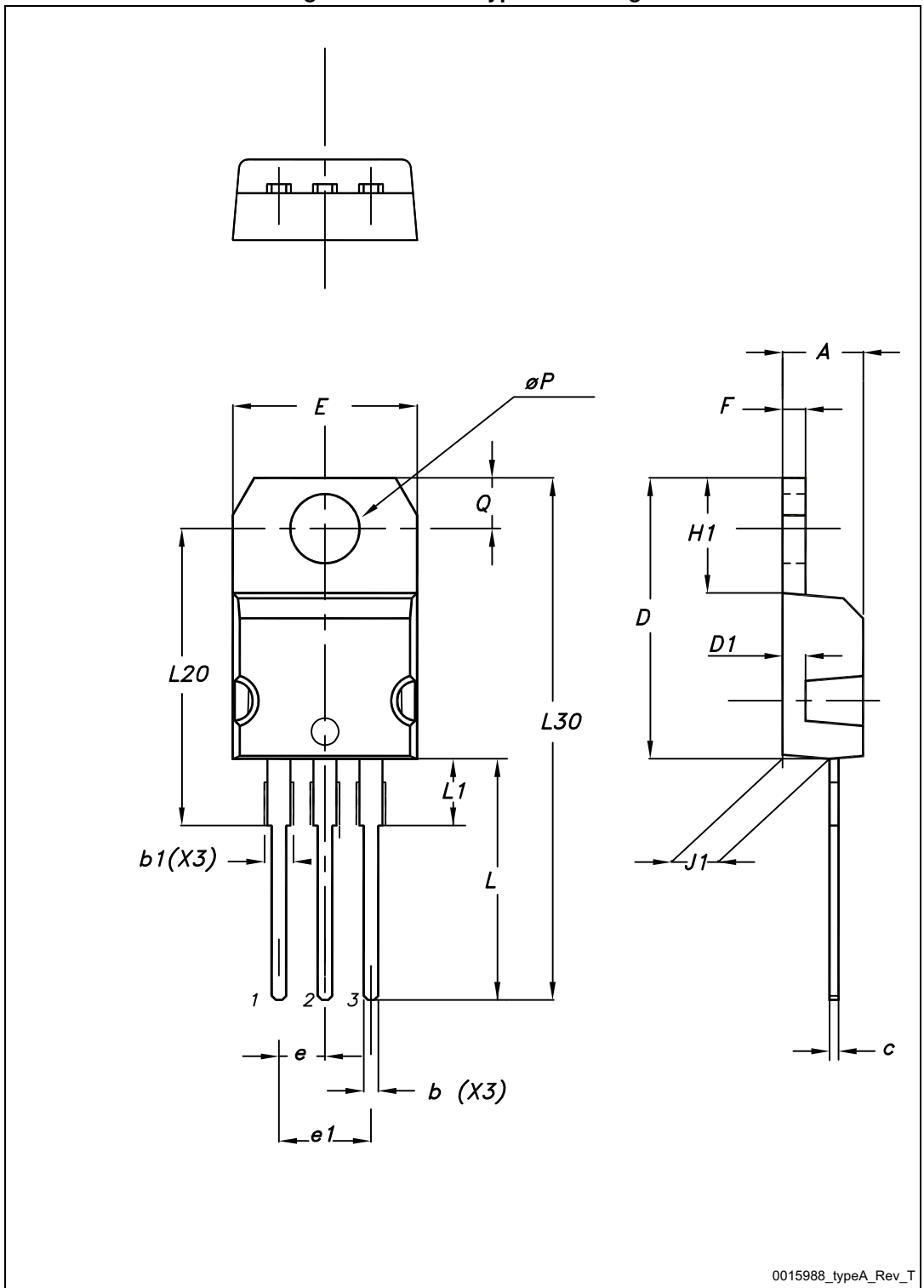


Table 10. TO-220FP mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.4		4.6
B	2.5		2.7
D	2.5		2.75
E	0.45		0.7
F	0.75		1
F1	1.15		1.70
F2	1.15		1.70
G	4.95		5.2
G1	2.4		2.7
H	10		10.4
L2		16	
L3	28.6		30.6
L4	9.8		10.6
L5	2.9		3.6
L6	15.9		16.4
L7	9		9.3
Dia	3		3.2

### 4.3 STP25N80K5, TO-220

Figure 27. TO-220 type A drawing



0015988\_typeA\_Rev\_T



Table 11. TO-220 type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.70
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13		14
L1	3.50		3.93
L20		16.40	
L30		28.90	
ØP	3.75		3.85
Q	2.65		2.95

4.4 STW25N80K5, TO-247

Figure 28. TO-247 drawing

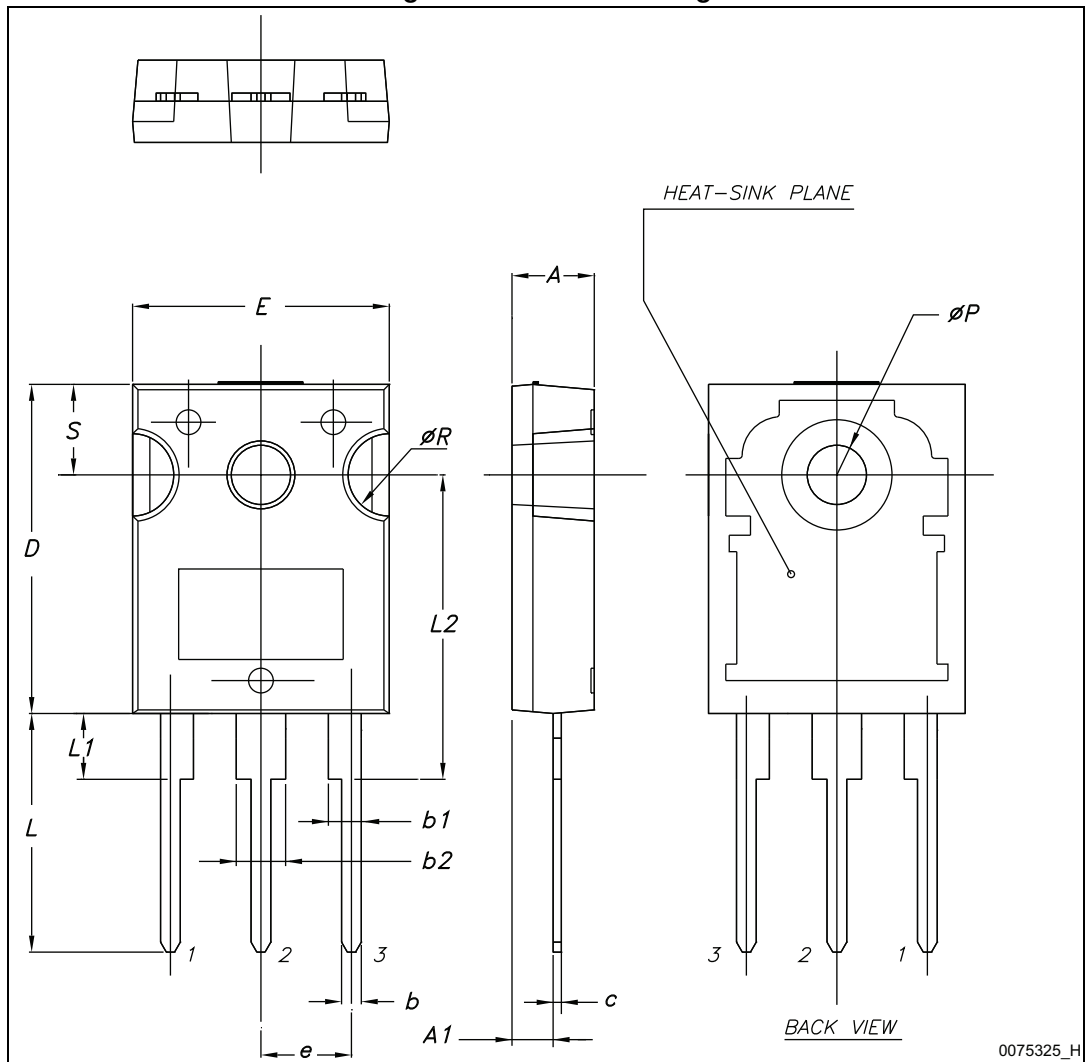


Table 12. TO-247 mechanical data

Dim.	mm.		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70

# 5 Packaging information

Figure 29. Tape

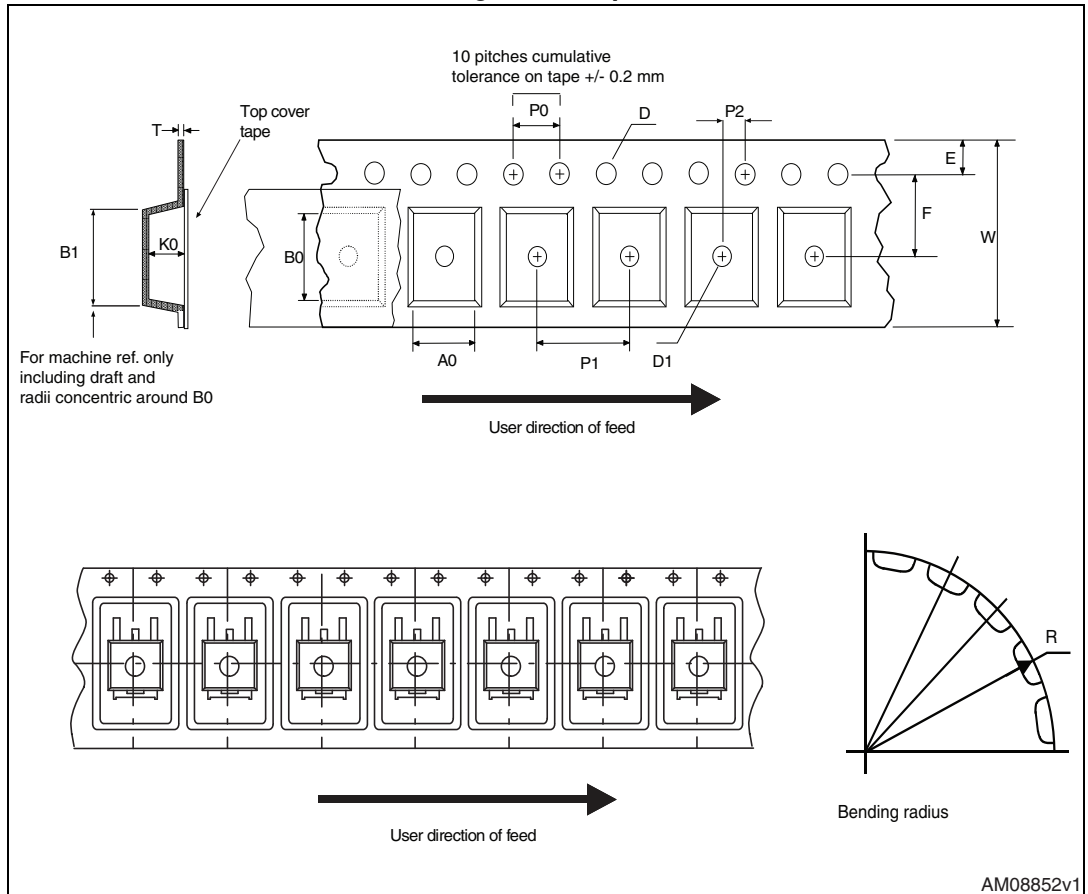


Figure 30. Reel

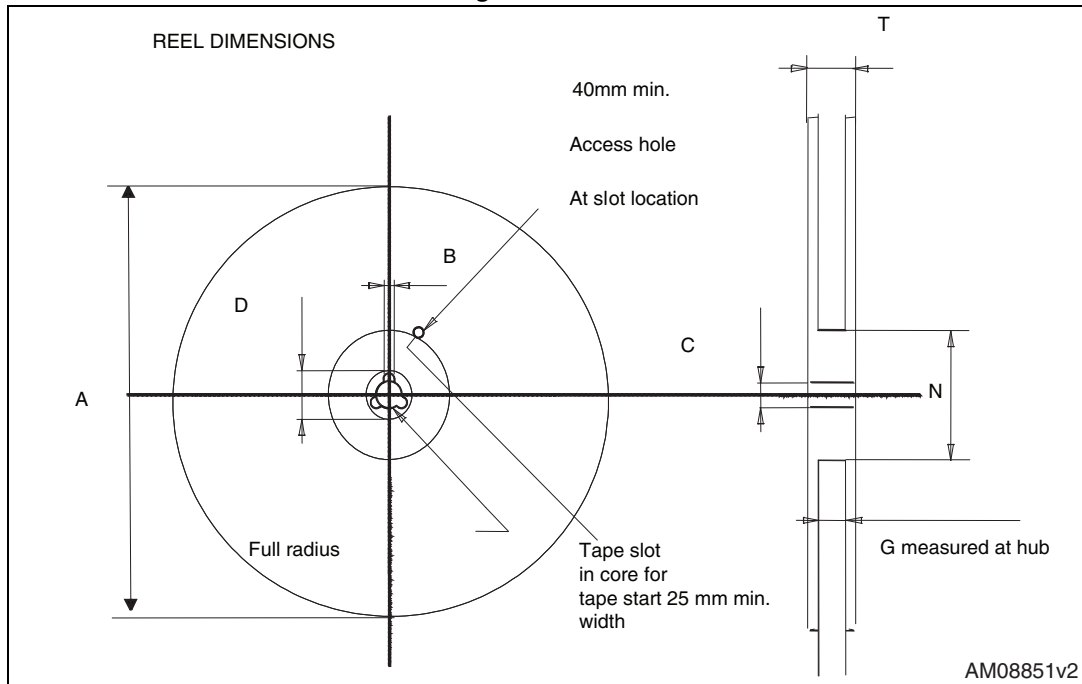


Table 13. D<sup>2</sup>PAK (TO-263) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	10.5	10.7	A		330
B0	15.7	15.9	B	1.5	
D	1.5	1.6	C	12.8	13.2
D1	1.59	1.61	D	20.2	
E	1.65	1.85	G	24.4	26.4
F	11.4	11.6	N	100	
K0	4.8	5.0	T		30.4
P0	3.9	4.1			
P1	11.9	12.1		Base qty	1000
P2	1.9	2.1		Bulk qty	1000
R	50				
T	0.25	0.35			
W	23.7	24.3			

## 6 Revision history

**Table 14. Document revision history**

Date	Revision	Changes
17-Jul-2012	1	First release.
04-Jun-2013	2	<ul style="list-style-type: none"> <li>– Modified: <math>I_{AR}</math>, <math>E_{AS}</math>, <math>dv/dt</math> on <a href="#">Table 2</a>, <math>R_{DS(on)}</math> value on <a href="#">Table 4</a>, entire values on <a href="#">Table 5</a>, <a href="#">6</a> and <a href="#">7</a></li> <li>– Updated: <a href="#">Section 4: Package mechanical data</a></li> <li>– Minor text changes</li> <li>– Updated: <a href="#">Table 11</a> and <a href="#">Figure 27</a></li> <li>– Document status promoted from preliminary data to production data</li> </ul>
31-Oct-2014	3	<p>Updated title, description and features in cover page.  Updated <a href="#">Figure 12: Static drain-source on-resistance</a>.  Updated <a href="#">Section 4.1: STB25N80K5, D<sup>2</sup>PAK</a> and <a href="#">Section 4.4: STW25N80K5, TO-247</a>  Minor text change</p>

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